Welcome to E-XFL.COM

What is "**Embedded - Microcontrollers**"?

"**Embedded - Microcontrollers**" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.
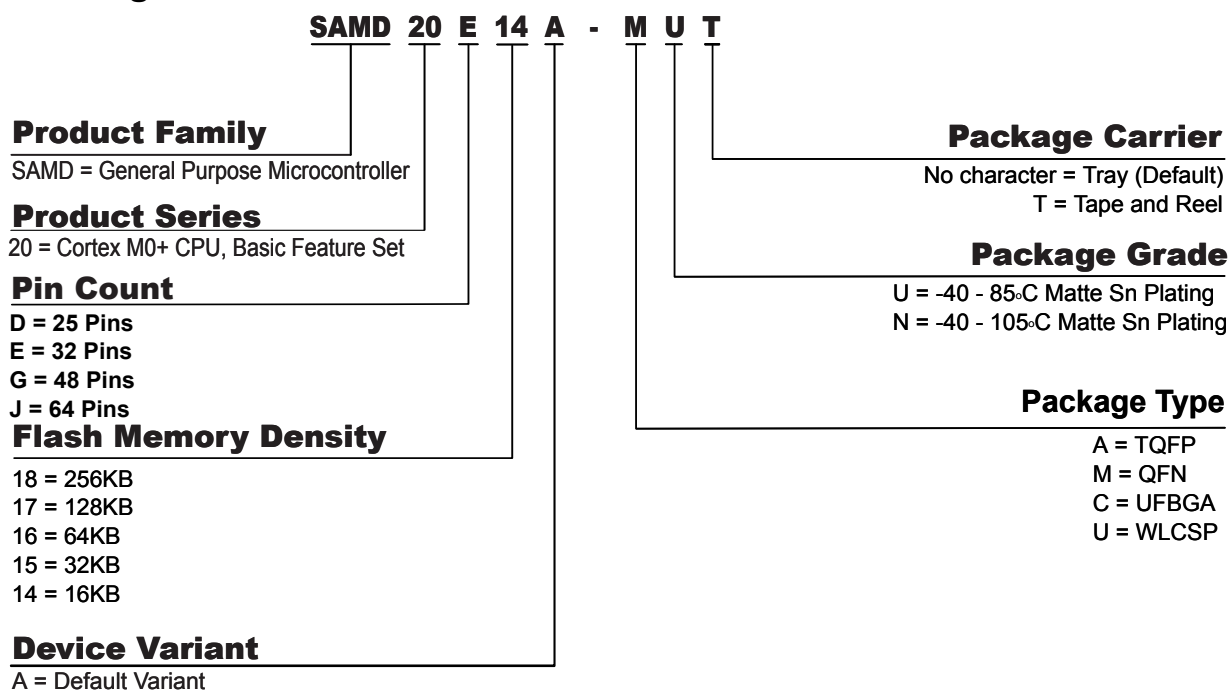
Applications of "**Embedded - Microcontrollers**"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	38
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 14x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamd20g18a-an

2. Configuration Summary

	SAM D20J	SAM D20G	SAM D20E
Pins	64	48	32
General Purpose I/O-pins (GPIOs)	52	38	26
Flash	256/128/64/32KB	256/128/64/32KB	256/128/64/32KB
SRAM	32/16/8/4/2KB	32/16/8/4/2KB	32/16/8/4/2KB
Timer Counter (TC) instances	8	6	6
Waveform output channels per TC instance	2	2	2
Serial Communication Interface (SERCOM) instances	6	6	4
Analog-to-Digital Converter (ADC) channels	20	14	10
Analog Comparators (AC)	2	2	2
Digital-to-Analog Converter (DAC) channels	1	1	1
Real-Time Counter (RTC)	Yes	Yes	Yes
RTC alarms	1	1	1
RTC compare values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values
External Interrupt lines	16	16	16
Peripheral Touch Controller (PTC) X and Y lines	16x16	12x10	10x6
Maximum CPU frequency	48MHz		
Packages	QFN TQFP UFBGA	QFN TQFP WLCSP	QFN TQFP
Oscillators	32.768kHz crystal oscillator (XOSC32K) 0.4-32MHz crystal oscillator (XOSC) 32.768kHz internal oscillator (OSC32K) 32KHz ultra-low-power internal oscillator (OSCULP32K) 8MHz high-accuracy internal oscillator (OSC8M) 48MHz Digital Frequency Locked Loop (DFLL48M)		
Event System channels	8	8	8
SW Debug Interface	Yes	Yes	Yes
Watchdog Timer (WDT)	Yes	Yes	Yes

3. Ordering Information

SAMD 20 E 14 A - M U T

Product Family
SAMD = General Purpose Microcontroller

Product Series
20 = Cortex M0+ CPU, Basic Feature Set

Pin Count
D = 25 Pins
E = 32 Pins
G = 48 Pins
J = 64 Pins

Flash Memory Density
18 = 256KB
17 = 128KB
16 = 64KB
15 = 32KB
14 = 16KB

Device Variant
A = Default Variant

Package Carrier
No character = Tray (Default)
T = Tape and Reel

Package Grade
U = -40 - 85∘C Matte Sn Plating
N = -40 - 105∘C Matte Sn Plating

Package Type
A = TQFP
M = QFN
C = UFBGA
U = WLCSP

3.1. SAM D20E

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20E14A-AU	16K	2K	TQFP32	Tray
ATSAMD20E14A-AUT				Tape & Reel
ATSAMD20E14A-AN				Tray
ATSAMD20E14A-ANT				Tape & Reel
ATSAMD20E14A-MU			QFN32	Tray
ATSAMD20E14A-MUT				Tape & Reel
ATSAMD20E14A-MN				Tray
ATSAMD20E14A-MNT				Tape & Reel

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20J18A-AU	256K	32K	TQFP64	Tray
ATSAMD20J18A-AUT				Tape & Reel
ATSAMD20J18A-AN				Tray
ATSAMD20J18A-ANT				Tape & Reel
ATSAMD20J18A-MU			QFN64	Tray
ATSAMD20J18A-MUT				Tape & Reel
ATSAMD20J18A-MN				Tray
ATSAMD20J18A-MNT				Tape & Reel
ATSAMD20J18A-CU			UFBGA64	Tray
ATSAMD20J18A-CUT				Tape & Reel

3.4. Device Identification

The DSU - Device Service Unit peripheral provides the Device Selection bits in the Device Identification register (DID.DEVSEL) in order to identify the device by software. The device variants have a reset value of DID=0x1001drxx, with the LSB identifying the die number ('d'), the die revision ('r') and the device selection ('xx').
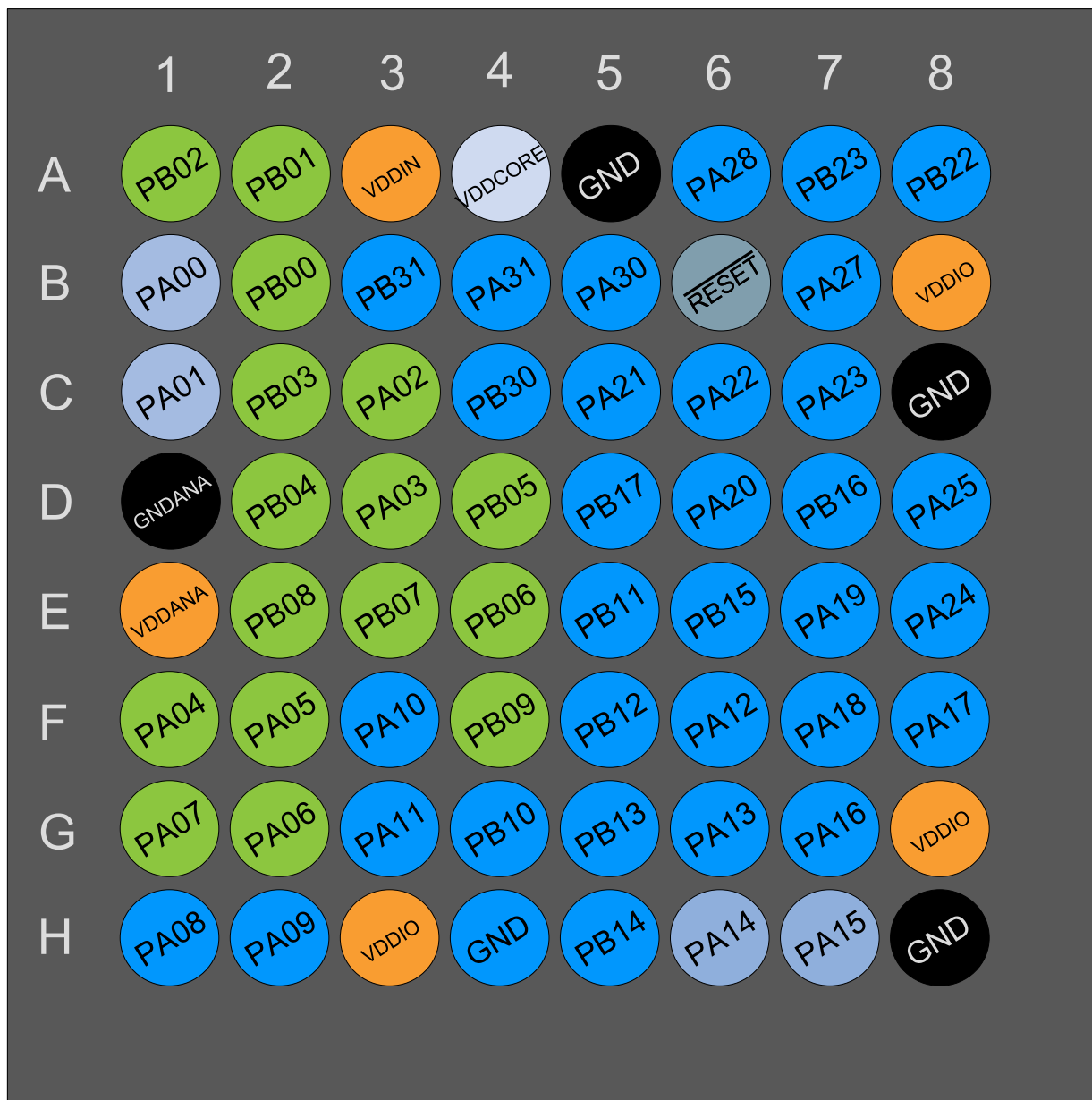
Table 3-1. Device Identification Values

Device Variant	DID.DEVSEL	Device ID (DID)
SAMD20J18C	0x00	0x10001300
SAMD20J18A	0x00	0x10001300
SAMD20J17A	0x01	0x10001301
SAMD20J16A	0x02	0x10001302
SAMD20J15A	0x03	0x10001303
SAMD20J14A	0x04	0x10001304
SAMD20G18A	0x05	0x10001305
SAMD20G17A	0x06	0x10001306
SAMD20G16A	0x07	0x10001307
SAMD20G15A	0x08	0x10001308
SAMD20G14A	0x09	0x10001309
SAMD20E18A	0x0A	0x1000130A
SAMD20E17A	0x0B	0x1000130B
SAMD20E16A	0x0C	0x1000130C
SAMD20E15A	0x0D	0x1000130D

Device Variant	DID.DEVSEL	Device ID (DID)
SAMD20E14A	0x0E	0x1000130E
Reserved	0x0F	
SAMD20G18U	0x10	0x10001310
SAMD20G17U	0x11	0x10001311
Reserved	0x12 - 0xFF	

Note: The device variant (last letter of the ordering number) is independent of the die revision (DSU.DID.REVISION): The device variant denotes functional differences, whereas the die revision marks evolution of the die. The device variant denotes functional differences, whereas the die revision marks evolution of the die.

5.1.2.   UFBGA64

	1	2	3	4	5	6	7	8
A	PB02	PB01	VDDIN	VDDCORE	GND	PA28	PB23	PB22
B	PA00	PB00	PB31	PA31	PA30	RESET	PA27	VDDIO
C	PA01	PB03	PA02	PB30	PA21	PA22	PA23	GND
D	GNDANA	PB04	PA03	PB05	PB17	PA20	PB16	PA25
E	VDDANA	PB08	PB07	PB06	PB11	PB15	PA19	PA24
F	PA04	PA05	PA10	PB09	PB12	PA12	PA18	PA17
G	PA07	PA06	PA11	PB10	PB13	PA13	PA16	VDDIO
H	PA08	PA09	VDDIO	GND	PB14	PA14	PA15	GND

- ▬ DIGITAL PIN
- ▬ ANALOG PIN
- ▬ OSCILLATOR
- ▬ GROUND
- ▬ INPUT SUPPLY
- ▬ REGULATED OUTPUT SUPPLY
- ▬ RESET PIN

5.3. SAM D20E

5.3.1. QFN32 / TQFP32

DIGITAL PIN
ANALOG PIN
OSCILLATOR
GROUND
INPUT SUPPLY
REGULATED OUTPUT SUPPLY
RESET PIN
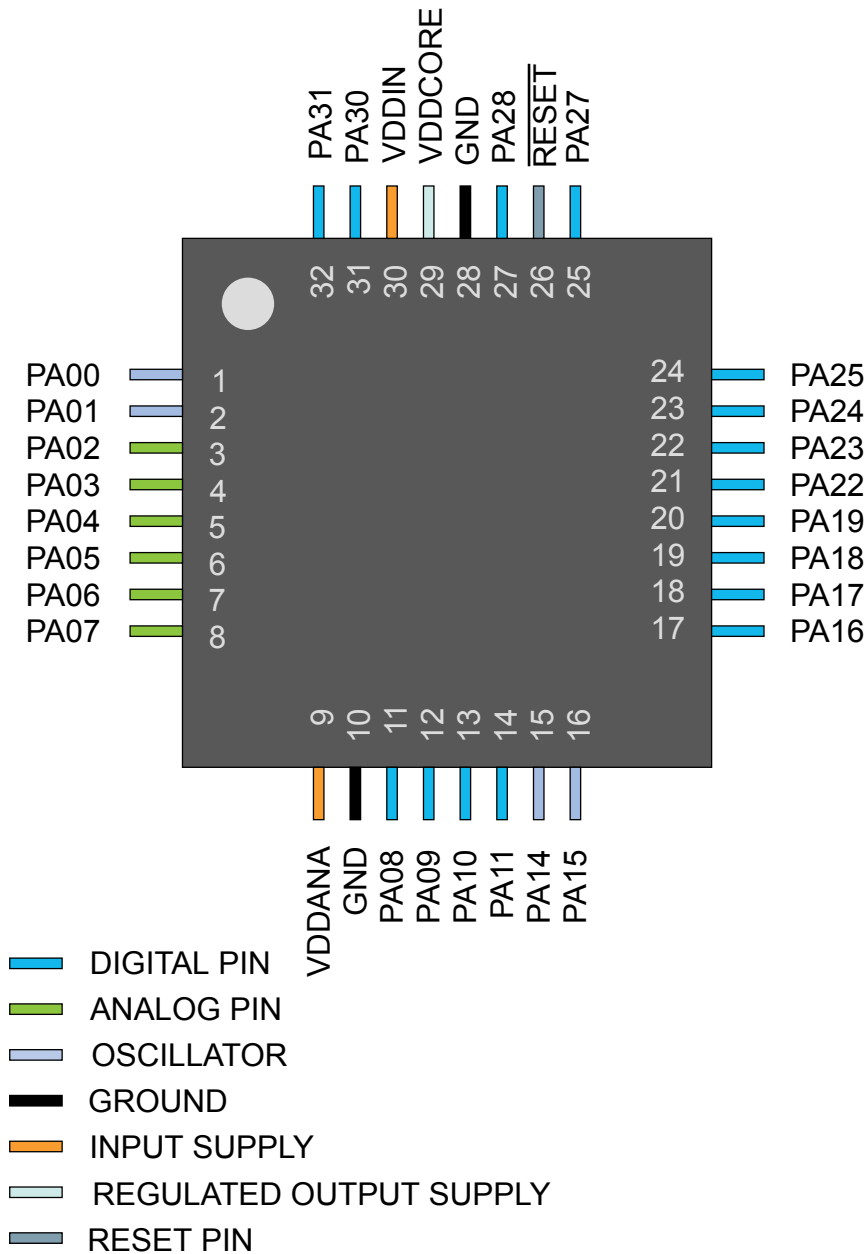
7. Processor And Architecture

7.1. Cortex M0+ Processor

The SAM D20 implements the ARM® Cortex®-M0+ processor, based on the ARMv6 Architecture and Thumb®-2 ISA. The Cortex M0+ is 100% instruction set compatible with its predecessor, the Cortex-M0 core, and upward compatible to Cortex-M3 and M4 cores. The ARM Cortex-M0+ implemented is revision r0p1. For more information refer to http://www.arm.com.

7.1.1. Cortex M0+ Configuration

Table 7-1. Cortex M0+ Configuration

Features	Configurable option	Device configuration
Interrupts	External interrupts 0-32	28
Data endianness	Little-endian or big-endian	Little-endian
SysTick timer	Present or absent	Present
Number of watchpoint comparators	0, 1, 2	2
Number of breakpoint comparators	0, 1, 2, 3, 4	4
Halting debug support	Present or absent	Present
Multiplier	Fast or small	Fast (single cycle)
Single-cycle I/O port	Present or absent	Present
Wake-up interrupt controller	Supported or not supported	Not supported
Vector Table Offset Register	Present or absent	Present
Unprivileged/Privileged support	Present or absent	Absent[1]
Memory Protection Unit	Not present or 8-region	Not present
Reset all registers	Present or absent	Absent
Instruction fetch width	16-bit only or mostly 32-bit	32-bit

Note:
 1. All software run in privileged mode only.

The ARM Cortex-M0+ core has two bus interfaces:
 • Single 32-bit AMBA-3 AHB-Lite system interface that provides connections to peripherals and all system memory, which includes flash and RAM.
 • Single 32-bit I/O port bus interfacing to the PORT with 1-cycle loads and stores.

7.1.2. Cortex-M0+ Peripherals

 • System Control Space (SCS)
   – The processor provides debug through registers in the SCS. Refer to the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
 • System Timer (SysTick)

Peripheral Source	NVIC Line
DAC – Digital-to-Analog Converter	23
PTC – Peripheral Touch Controller	24

7.3. Micro Trace Buffer

7.3.1. Features
- Program flow tracing for the Cortex-M0+ processor
- MTB SRAM can be used for both trace and general purpose storage by the processor
- The position and size of the trace buffer in SRAM is configurable by software
- CoreSight compliant

7.3.2. Overview
When enabled, the MTB records changes in program flow, reported by the Cortex-M0+ processor over the execution trace interface shared between the Cortex-M0+ processor and the CoreSight MTB-M0+. This information is stored as trace packets in the SRAM by the MTB. An off-chip debugger can extract the trace information using the Debug Access Port to read the trace information from the SRAM. The debugger can then reconstruct the program flow from this information.

The MTB simultaneously stores trace information into the SRAM, and gives the processor access to the SRAM. The MTB ensures that trace write accesses have priority over processor accesses.

The execution trace packet consists of a pair of 32-bit words that the MTB generates when it detects the processor PC value changes non-sequentially. A non-sequential PC change can occur during branch instructions or during exception entry. See the CoreSight MTB-M0+ Technical Reference Manual for more details on the MTB execution trace packet format.

Tracing is enabled when the MASTER.EN bit in the Master Trace Control Register is 1. There are various ways to set the bit to 1 to start tracing, or to 0 to stop tracing. See the CoreSight Cortex-M0+ Technical Reference Manual for more details on the Trace start and stop and for a detailed description of the MTB's MASTER register. The MTB can be programmed to stop tracing automatically when the memory fills to a specified watermark level or to start or stop tracing by writing directly to the MASTER.EN bit. If the watermark mechanism is not being used and the trace buffer overflows, then the buffer wraps around overwriting previous trace packets.

The base address of the MTB registers is 0x41006000; this address is also written in the CoreSight ROM Table. The offset of each register from the base address is fixed and as defined by the CoreSight MTB-M0+ Technical Reference Manual. The MTB has 4 programmable registers to control the behavior of the trace features:

- POSITION: Contains the trace write pointer and the wrap bit,
- MASTER: Contains the main trace enable bit and other trace control fields,
- FLOW: Contains the WATERMARK address and the AUTOSTOP and AUTOHALT control bits,
- BASE: Indicates where the SRAM is located in the processor memory map. This register is provided to enable auto discovery of the MTB SRAM location, by a debug agent.

See the CoreSight MTB-M0+ Technical Reference Manual for a detailed description of these registers.

7.4. High-Speed Bus System

7.4.1. Features

High-Speed Bus Matrix has the following features:
- Symmetric crossbar bus switch implementation
- Allows concurrent accesses from different masters to different slaves
- 32-bit data bus
- Operation at a one-to-one clock frequency with the bus masters

7.4.2. Configuration

Table 7-4. Bus Matrix Masters

Bus Matrix Masters	Master ID
CM0+ - Cortex M0+ Processor	0
DSU - Device Service Unit	1

Table 7-5. Bus Matrix Slaves

Bus Matrix Slaves	Slave ID
Internal Flash Memory	0
AHB-APB Bridge A	1
AHB-APB Bridge B	2
AHB-APB Bridge C	3

7.5. AHB-APB Bridge

The AHB-APB bridge is an AHB slave, providing an interface between the high-speed AHB domain and the low-power APB domain. It is used to provide access to the programmable control registers of peripherals (see *Product Mapping*).

AHB-APB bridge is based on AMBA APB Protocol Specification V2.0 (ref. as APB4) including:
- Wait state support
- Error reporting
- Transaction protection
- Sparse data transfer (byte, half-word and word)

Additional enhancements:
- Address and data cycles merged into a single cycle
- Sparse data transfer also apply to read access

to operate the AHB-APB bridge, the clock (CLK_HPBx_AHB) must be enabled. See *PM – Power Manager* for details.

Figure 7-1. APB Write Access.

No wait states

Wait states
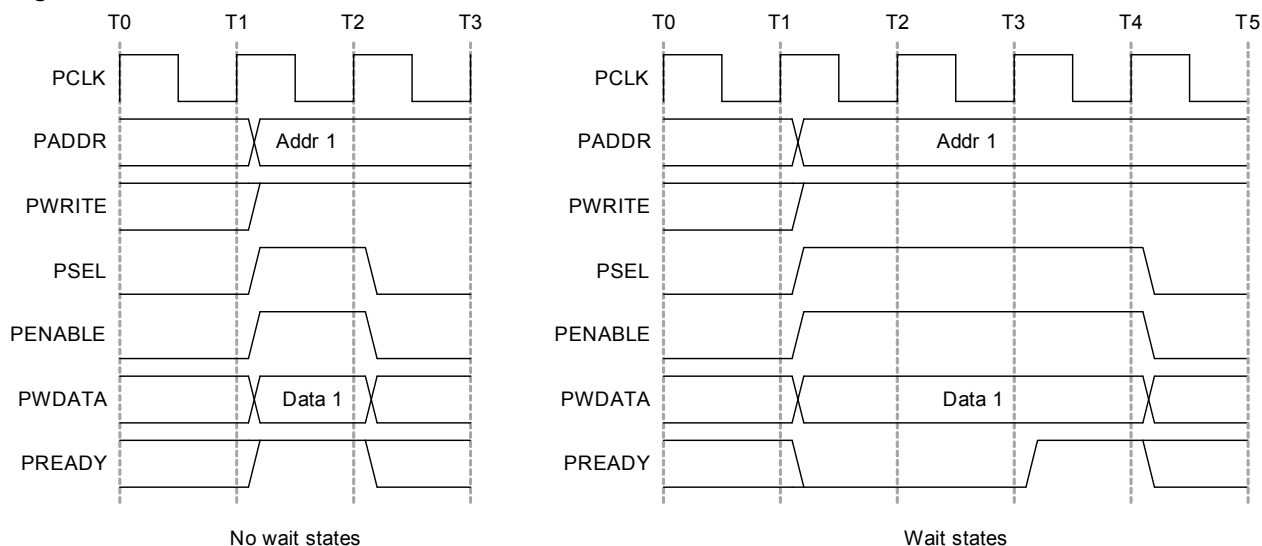
Figure 7-2. APB Read Access.

No wait states

Wait states
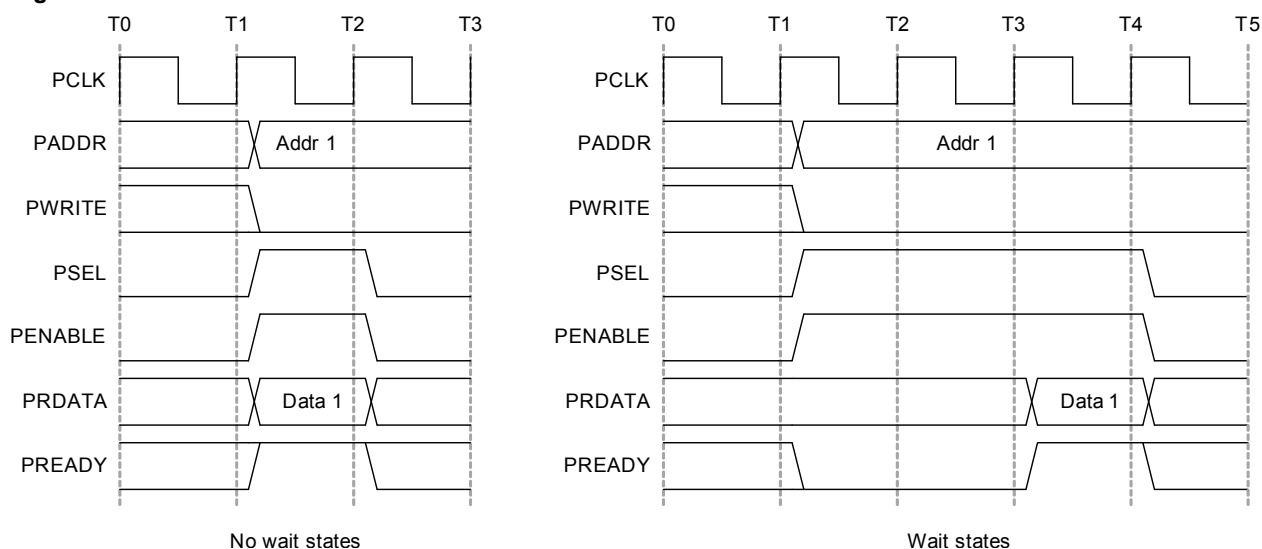
Related Links

7.6. PAC - Peripheral Access Controller

7.6.1. Overview

There is one PAC associated with each AHB-APB bridge. The PAC can provide write protection for registers of each peripheral connected on the same bridge.

The PAC peripheral bus clock (CLK_PACx_APB) can be enabled and disabled in the Power Manager. CLK_PAC0_APB and CLK_PAC1_APB are enabled are reset. CLK_PAC2_APB is disabled at reset. Refer to *PM – Power Manager* for details. The PAC will continue to operate in any sleep mode where the selected clock source is running. Write-protection does not apply for debugger access. When the debugger makes an access to a peripheral, write-protection is ignored so that the debugger can update the register.

7.7.2.2. Write Protect Set

Name: WPSET
Offset: 0x04
Reset: 0x000002
Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
Access								
Reset								

Bit	15	14	13	12	11	10	9	8
Access								
Reset								

Bit	7	6	5	4	3	2	1	0
		MTB			PORT	NVMCTRL	DSU	
Access		R/W			R/W	R/W	R/W	
Reset		0			0	0	1	

Bit 6 – MTB

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – PORT

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – NVMCTRL

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – DSU

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

7.7.3. PAC2 Register Description

7.7.3.2. Write Protect Set

Name: WPSET
Offset: 0x04
Reset: 0x00800000
Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
					PTC	DAC	AC	ADC
Access					R/W	R/W	R/W	R/W
Reset					0	0	0	0

Bit	15	14	13	12	11	10	9	8
	TC7	TC6	TC5	TC4	TC3	TC2	TC1	TC0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

Bit	7	6	5	4	3	2	1	0
	SERCOM5	SERCOM4	SERCOM3	SERCOM2	SERCOM1	SERCOM0	EVSYS	
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Reset	0	0	0	0	0	0	0	

Bit 19 – PTC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 18 – DAC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 17 – AC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 16 – ADC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 15,14,13,12,11,10,9,8 – TCx
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 7,6,5,4,3,2 – SERCOMx
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – EVSYS
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

8. Packaging Information

8.1. Thermal Considerations

Related Links

Junction Temperature on page 39

8.1.1. Thermal Resistance Data

The following *table* summarizes the thermal resistance data depending on the package.

Table 8-1. Thermal Resistance Data

Package Type	θ_{JA}	θ_{JC}
32-pin TQFP	68.0°C/W	25.8°C/W
48-pin TQFP	78.8°C/W	12.3°C/W
64-pin TQFP	66.7°C/W	11.9°C/W
32-pin QFN	37.2°C/W	13.1°C/W
48-pin QFN	33.0°C/W	11.4°C/W
64-pin QFN	33.5°C/W	11.2°C/W
64-ball UFBGA	67.4°C/W	12.4°C/W
45-ball WLCSP	37.0°C/W	0.36°C/W

8.1.2. Junction Temperature

The average chip-junction temperature, T_J, in °C can be obtained from the following:

1. $T_J = T_A + (P_D \times \theta_{JA})$
2. $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

where:

- θ_{JA} = Package thermal resistance, Junction-to-ambient (°C/W), see Thermal Resistance Data
- θ_{JC} = Package thermal resistance, Junction-to-case thermal resistance (°C/W), see Thermal Resistance Data
- $\theta_{HEATSINK}$ = Thermal resistance (°C/W) specification of the external cooling device
- P_D = Device power consumption (W)
- T_A = Ambient temperature (°C)

From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T_J in °C.

Related Links

Thermal Considerations on page 39

Table 8-4. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.2. 64 pin QFN

DRAWINGS NOT SCALED

TOP VIEW

SIDE VIEW

BOTTOM VIEW

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	-----	1.00	
D/E		9.00 BSC		
D2/E2	4.60	4.70	4.80	
J	0.00	-----	0.05	
b	0.15	0.20	0.25	
e		0.50 BSC		
L	0.30	0.40	0.55	
N		64		

Option A — Pin 1# Chamfer (C 0.35)
Option B — Pin 1# Notch (0.20 R)

EXPOSED DIE ATTACH PAD

See Options A, B

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-220, Variation VMMD-4, for proper dimensions, tolerances, datums, etc.
2. Dimension b applies to metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
If the terminal has the optical radius on the other end of the terminal, the dimension should not be measured in that radius area.

05/27/2011

	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact: packagedrawings@atmel.com	PA, 64 Leads , 0.50 mm pitch, 9 x 9 x 1 mm Very Thin Quad Flat No Lead Package (VQFN) Sawn	ZST	PA	A

Note: The exposed die attach pad is not connected electrically inside the device.

Table 8-9. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-10. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E8

8.2.4.   48 pin TQFP
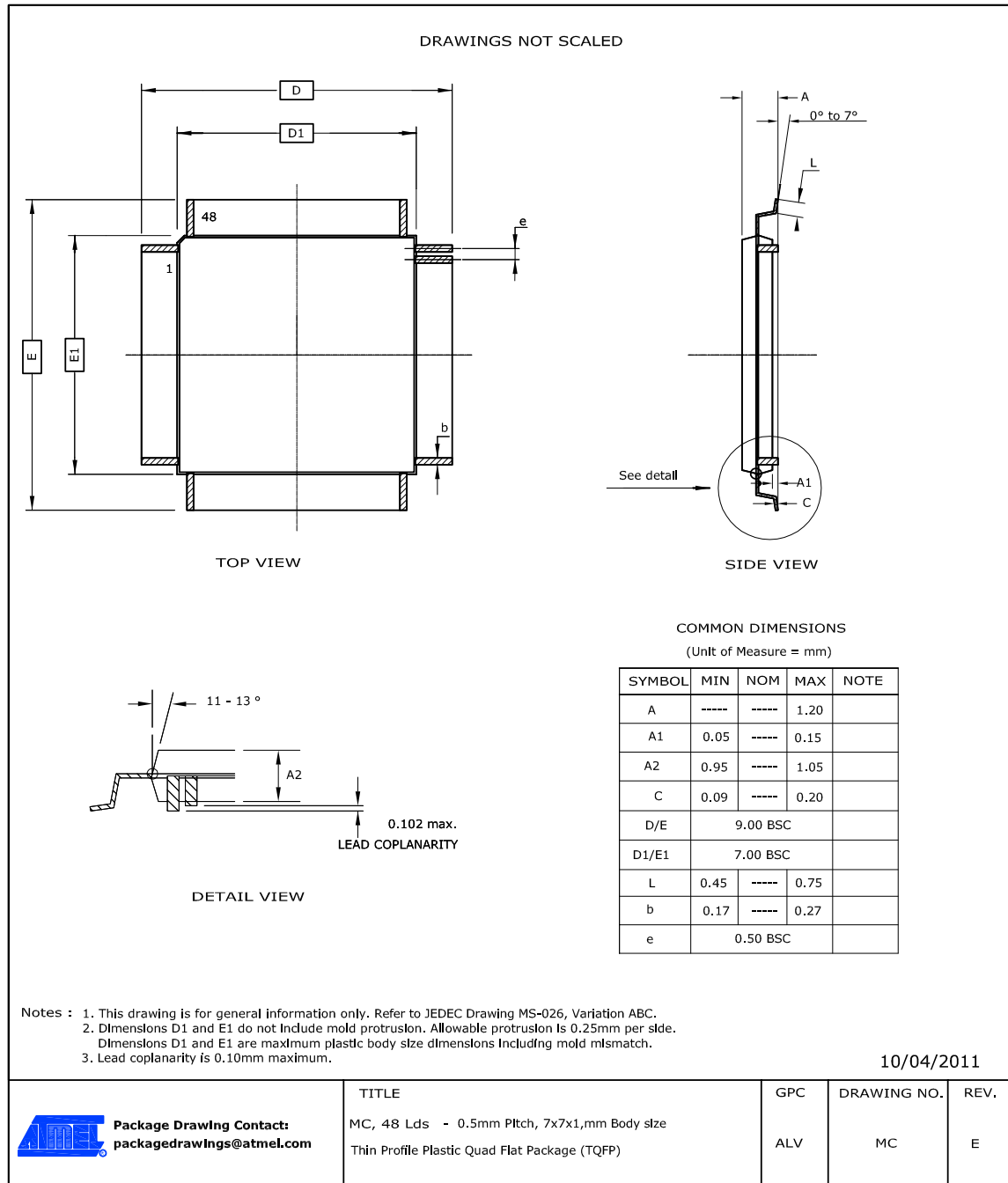
Table 8-11. Device and Package Maximum Weight

140	mg

Table 8-12. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-13. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

Table 8-22. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.8. 32 pin QFN

DRAWINGS NOT SCALED

TOP VIEW

SIDE VIEW

BOTTOM VIEW

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	----	1.00	
A1	0.00	----	0.05	
D/E	5.00 BSC			
D2/E2	3.50	3.60	3.70	
L	0.30	0.40	0.50	
b	0.18	0.25	0.30	2
e	0.50 BSC			
n	32			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-220, Variation VHHD-5, for proper dimensions, tolerances, datums, etc.
2. Dimension b applies to metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
If the terminal has the optical radius on the other end of the terminal, the dimension should not be measured in that radius area.

10/05/2015

Package Drawing Contact: packagedrawings@atmel.com	TITLE PG, 32 Leads , 0.50mm pitch, 5x5x1.0mm Body Size Very Thin Quad Flat No Lead Package (VQFN) Sawn	GPC ZKV	DRAWING NO. PG	REV. C

Note: The exposed die attach pad is connected inside the device to GND and GNDANA.

Table 8-23. Device and Package Maximum Weight

90	mg

Table 8-24. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-25. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.9. 35 ball WLCSP

DRAWINGS NOT SCALED

∅ 0.015 Ⓜ C
∅ 0.05 Ⓜ C A B
b=∅ 0.260+/-0.030 (35X)

PIN A1 CORNER

TOP VIEW

-B-

2.529+/-0.03

2.821+/-0.03

-A-

0.03 (4X)

BOTTOM VIEW

0.20
2.000
0.400
0.400
0.20
2.000

SIDE VIEW

0.075 C
C
0.483 max
0.20 +/- 0.03
SEATING PLANE
Backside Coating : 0.04mm
0.203 +/- 0.025

COMMON DIMENSIONS
(Unit of Measure = mm)

BALL	SIGNAL	X COORD	Y COORD
A1	PA00	1	-1
A2	PA01	0.6	-0.6
A3	GNDANA	0.2	-0.2
A4	VDDANA	-0.2	0.2
A5	PA06	1	0.4
A6	VDDIO	1	1
B1	PA30	0.6	-1
B2	PA31	0.2	-0.6
B3	PA02	-0.2	-0.2
B4	PA04	1	0.2
B5	PA07	1	0.4
B6	NO BALL		
C1	VDDCORE	0.2	-1
C2	VDDIO	-0.2	-0.6
C3	PA03	1	-0.2
C4	PA05	1	0.2
C5	PA08	0.6	0.4
C6	PA10	0.2	1
D1	GND	-0.2	-1
D2	PA28	1	-0.6
D3	GND	1	-0.2
D4	PA11	0.6	0.2
D5	PA09	0.2	0.4

BALL	SIGNAL	X COORD	Y COORD
D6	GND	-0.2	1
E1	RESET_N	1	-1
E2	PA27	1	-0.6
E3	PA22	0.6	-0.2
E4	PA17	0.2	0.2
E5	PA16	-0.2	0.4
E6	PA14	1	1
F1	PA25	1	-1
F2	PA24	0.6	-0.6
F3	PA23	0.2	-0.2
F4	PA19	-0.2	0.2
F5	PA18	1	0.4
F6	PA15	1	1

Notes : 1. Dimension "b" is measured at the maximum ball diameter in a plane to the seating plane.

01/07/2016

Package Drawing Contact:
packagedrawings@atmel.com

TITLE
35 ball - (6X6 Array), 0.4mm pitch
2.821 x 2.529 x 0.483mm, WLCSP
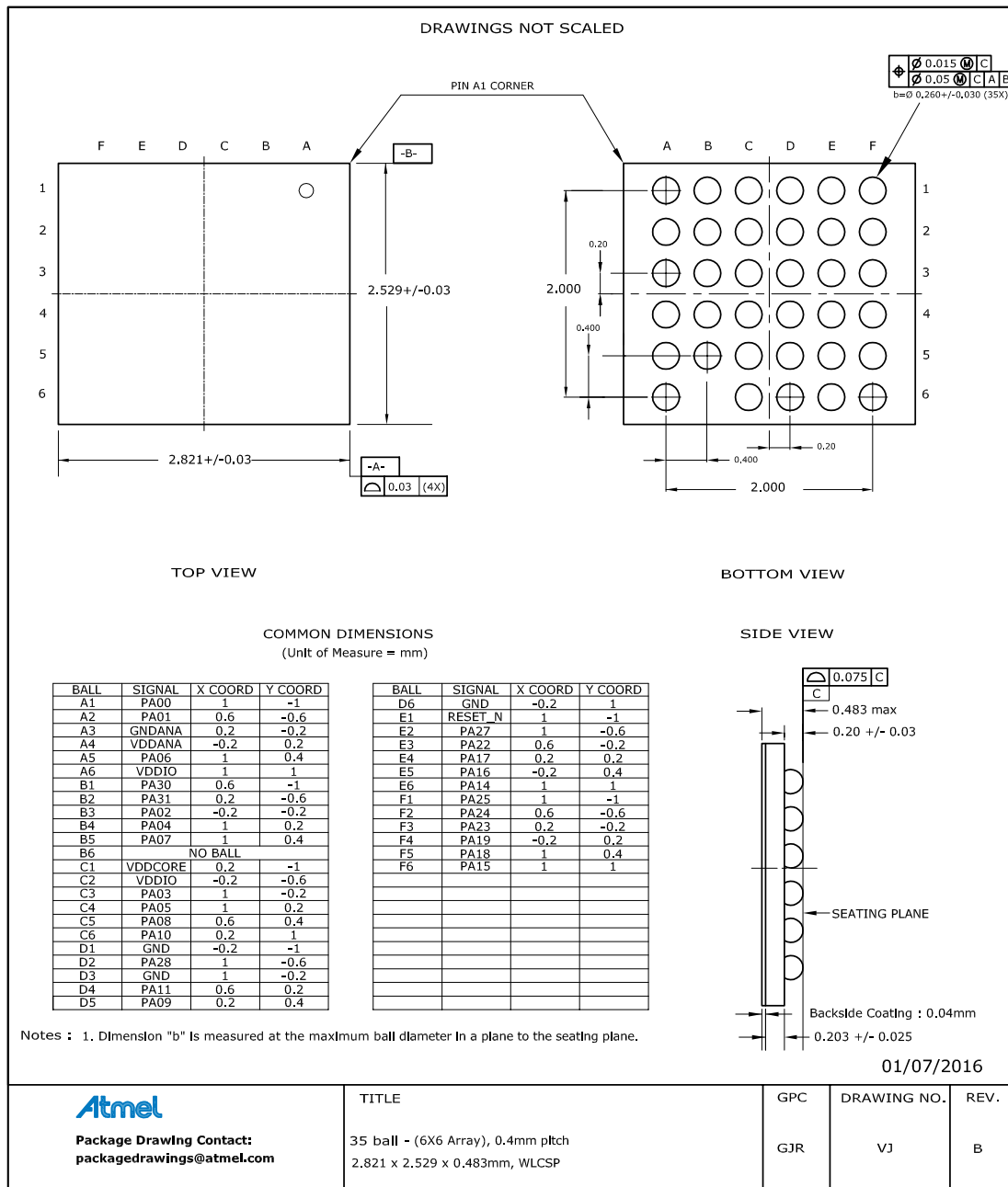
GPC	DRAWING NO.	REV.
GJR	VJ	B

Table 8-26. Device and Package Maximum Weight

6.2	mg